



EVG Technology Day

in Kyoto, Japan
May 30, 2019

Schedule

Thursday, May 30, 2019

12:30 | Registration
13:00 | EVG Technology Day
18:15 | Reception

Location

HYATT REGENCY KYOTO
644-2 Sanjusangendo-mawari,
Higashiyama-ku, Kyoto,
Japan, 605-0941

Register

The registration is free of charge.

For more information
and to register for free:

www.EVGroup.com/TechDayKyoto

TO NEW DIMENSIONS™

Agenda

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| 12:30 | Registration |
| 13:00 | Welcome and Introduction Hiroshi Yamamoto, Representative Director, EV Group Japan |
| 13:10 | Keynote - Monolithic 3D LSI and Electronic-Photonic Integration Using Wafer Bonding Dr. Mitsuru Takenaka, Associate Professor, Dept. of Electrical Engineering and Information Systems, University of Tokyo |
| 13:50 | Wafer Bonding Technologies Enabling 3D Integration Dr. Yudai Miyawaki & Hirokazu Kurotaki, Process Technology Engineers, EV Group Japan |
| 14:35 | Coffee Break |
| 14:55 | Wafer Level Molding and Nano Imprinting Enabling Next Generation Photonic Devices Christine Thanner, Technology Development, EV Group (EVG) |
| 15:40 | Keynote - Process Technology for Image Sensor in Foundry Business Dr. Atsushi Ikeda, Deputy Director of Process R&D and General Manager, PhD., Process Technology Group, Process Technology Center, TowerJazz Panasonic Semiconductor Co., Ltd. |
| 16:20 | Coffee Break |
| 16:40 | Keynote - Surface Modification and Bonding Technology Significant in Near Future Electronics Dr. Kyoichi Suguro, Manager, New Materials and Technology Laboratory, Environment Energy Laboratory, R&D Center, Carlit Holdings Co., Ltd. |
| 17:20 | To New Dimensions™ - Market Trends for a Connected World Dr. Martin Eibelhuber, Deputy Business Development, EV Group (EVG) |
| 18:00 | Open Discussion & Closing Remarks Hiroshi Yamamoto, Representative Director, EV Group Japan |
| 18:15 | Reception |

